

## Micropower Quad 10-Bit DAC

January 2000

### **FEATURES**

- Tiny: 4 DACs in the Board Space of an SO-8
- Micropower: 59μA per DAC Plus
   1μA Sleep Mode for Extended Battery Life
- Wide 2.7V to 5.5V Supply Range
- Rail-to-Rail Voltage Outputs Drive 1000pF
- Reference Range Includes Supply for Ratiometric 0V-to-V<sub>CC</sub> Output
- Reference Input Has Constant Impedance over All Codes—Eliminates External Reference Buffer
- Individually Addressable DACs
- Differential Nonlinearity: ≤ ±0.75LSB Max
- Pin-Compatible Octal Version Available (LTC1660)

### **APPLICATIONS**

- Mobile Communications
- Remote Industrial Devices
- Automatic Calibration for Manufacturing
- Portable Battery-Powered Instruments
- Trim/Adjust Applications

#### DESCRIPTION

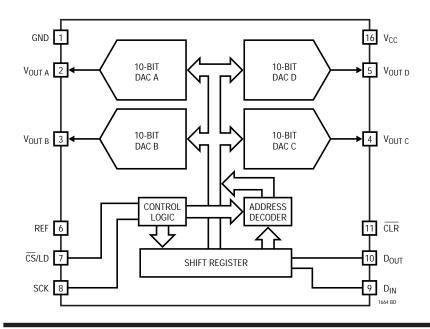
The LTC $^{\circ}$ 1664 integrates four accurate, serially addressable 10-bit digital-to-analog converters (DACs) in a tiny 16-pin Narrow SSOP package. Each buffered DAC draws just 59 $\mu$ A total supply current, yet is capable of supplying DC output currents in excess of 5mA and reliably driving capacitive loads of up to 1000pF. Sleep mode further reduces total supply current to 1 $\mu$ A.

Linear Technology's proprietary, inherently monotonic voltage interpolation architecture provides excellent linearity while allowing for an exceptionally small external form factor.

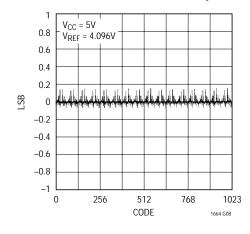
Ultralow supply current, power-saving Sleep mode and extremely compact size make the LTC1664 ideal for battery-powered applications, while its ease of use, high performance and wide supply range make it an excellent choice as a general purpose converter.

T, LTC and LT are registered trademarks of Linear Technology Corporation.

## **BLOCK DIAGRAM**



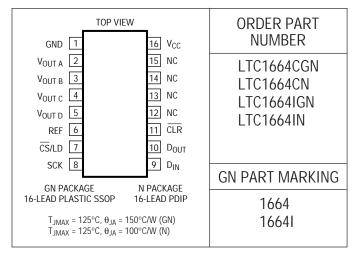
#### LTC1664 Differential Nonlinearity (DNL)





### ABSOLUTE MAXIMUM RATINGS

## PACKAGE/ORDER INFORMATION



Consult factory for Military grade parts.

## **ELECTRICAL CHARACTERISTICS**

The ullet denotes specifications which apply over the full operating temperature range, otherwise specifications are at  $T_A = 25^{\circ}C$ .  $V_{CC} = 2.7V$  to 5.5V,  $V_{REF} \leq V_{CC}$ ,  $V_{OUT}$  unloaded, unless otherwise noted.

SYMBOL	PARAMETER	CONDITONS		MIN	TYP	MAX	UNITS
Accuracy							
	Resolution		•	10			Bits
	Monotonicity	$1V \le V_{REF} \le V_{CC} - 0.1V \text{ (Note 2, 4)}$	•	10			Bits
DNL	Differential Nonlinearity	$1V \le V_{REF} \le V_{CC} - 0.1V$ (Note 2, 4)	•		±0.2	±0.75	LSB
INL	Integral Nonlinearity	$1V \le V_{REF} \le V_{CC} - 0.1V \text{ (Note 2, 4)}$	•		±0.6	±2.5	LSB
V <sub>OS</sub>	Offset Error	(Note 7)	•		±10	±30	mV
	V <sub>OS</sub> Temperature Coefficient		•		±15		μV/°C
FSE	Full-Scale Error	V <sub>CC</sub> = 5V, V <sub>REF</sub> = 4.096V (Note 4)	•		±3	±15	LSB
	Full-Scale Error Temperature Coefficient		•		±30		μV/°C
PSR	Power Supply Rejection	V <sub>REF</sub> = 2.5V			0.18		LSB/V
Reference	e Input						
	Input Voltage Range		•	0		V <sub>CC</sub>	V
	Resistance	Not in Sleep Mode	•	70	130		kΩ
	Capacitance	(Note 6)			15		pF
I <sub>REF</sub>	Reference Current	Sleep Mode	•		0.001	1	μΑ
Power Sup	pply						
$V_{CC}$	Positive Supply Voltage	For Specified Performance	•	2.7		5.5	V
I <sub>CC</sub>	Supply Current	V <sub>CC</sub> = 5V (Note 3) V <sub>CC</sub> = 3V (Note 3) Sleep Mode (Note 3)	•		236 186 1	380 290 3	μΑ μΑ μΑ



**ELECTRICAL CHARACTERISTICS**The ullet denotes specifications which apply over the full operating temperature range, otherwise specifications are at T<sub>A</sub> = 25°C. V<sub>CC</sub> = 2.7V to 5.5V, V<sub>REF</sub>  $\leq$  V<sub>CC</sub>, V<sub>OUT</sub> unloaded, unless otherwise noted.

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS	
DC Performance								
	Short-Circuit Current Low	V <sub>OUT</sub> = 0V, V <sub>CC</sub> = 5.5V, V <sub>REF</sub> = 5.1V, Code = Full Scale (Note 4)	•	10	30	100	mA	
	Short-Circuit Current High	V <sub>OUT</sub> = V <sub>CC</sub> = 5.5V, V <sub>REF</sub> = 5.1V, Code = 0 (Note 4)	•	10	27	120	mA	
AC Perform	mance							
	Voltage Output Slew Rate	Rising (Notes 4, 5) Falling (Notes 4, 5)			0.60 0.25		V/μs V/μs	
	Voltage Output Settling Time	To ±0.5LSB (Notes 4, 5)			30		μs	
	Capacitive Load Driving				1000		pF	
Digital I/O								
$V_{IH}$	Digital Input High Voltage	V <sub>CC</sub> = 2.7V to 5.5V V <sub>CC</sub> = 2.7V to 3.6V	•	2.4 2.0			V	
$V_{IL}$	Digital Input Low Voltage	V <sub>CC</sub> = 4.5V to 5.5V V <sub>CC</sub> = 2.7V to 5.5V	•			0.8 0.6	V	
V <sub>OH</sub>	Digital Output High Voltage	I <sub>OUT</sub> = -1mA, D <sub>OUT</sub> Only	•	V <sub>CC</sub> – 1			V	
$V_{OL}$	Digital Output Low Voltage	I <sub>OUT</sub> = 1mA, D <sub>OUT</sub> Only	•			0.4	V	
I <sub>LK</sub>	Digital Input Leakage	$V_{IN}$ = GND to $V_{CC}$	•			±10	μА	
C <sub>IN</sub>	Digital Input Capacitance	(Note 6)	•			10	pF	

**TIMING CHARACTERISTICS** The ullet denotes specifications which apply over the full operating temperature range, otherwise specifications are at  $T_A = 25^{\circ}C$ . (See Figure 1)

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
$V_{CC} = 4.5$	/ to 5.5V						
t <sub>1</sub>	D <sub>IN</sub> Valid to SCK Setup		•	40	15		ns
t <sub>2</sub>	D <sub>IN</sub> Valid to SCK Hold		•	0	-11		ns
$t_3$	SCK High Time	(Note 6)	•	30	5		ns
t <sub>4</sub>	SCK Low Time	(Note 6)	•	30	7		ns
t <sub>5</sub>	CS/LD Pulse Width	(Note 6)	•	80	30		ns
t <sub>6</sub>	LSB SCK High to CS/LD High	(Note 6)	•	30	4		ns
t <sub>7</sub>	CS/LD Low to SCK High	(Note 6)	•	80	26		ns
t <sub>8</sub>	D <sub>OUT</sub> Propagation Delay	C <sub>LOAD</sub> = 15pF (Note 6)	•	5	26	80	ns
t <sub>9</sub>	SCK Low to CS/LD Low	(Note 6)	•	20	0		ns
t <sub>10</sub>	CLR Pulse Width	(Note 6)	•	100	37		ns
t <sub>11</sub>	CS/LD High to SCK Positive Edge	(Note 6)	•	30	0		ns
	SCK Frequency	Continuous Square Wave (Note 6) Continuous 23% Duty Cycle Pulse (Note 6) Gated Square Wave (Note 6)	•			5.00 7.69 16.7	MHz MHz MHz
$V_{CC} = 2.7$	/ to 5.5V						
t <sub>1</sub>	D <sub>IN</sub> Valid to SCK Setup	(Note 6)	•	60	20		ns
$t_2$	D <sub>IN</sub> Valid to SCK Hold	(Note 6)	•	0	-14		ns
t <sub>3</sub>	SCK High Time	(Note 6)	•	50	8		ns
t <sub>4</sub>	SCK Low Time	(Note 6)	•	50	12		ns
t <sub>5</sub>	CS/LD Pulse Width	(Note 6)	•	100	30		ns



# **TIMING CHARACTERISTICS** The $\bullet$ denotes specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^{\circ}C$ . (See Figure 1)

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
t <sub>6</sub>	LSB SCK High to CS/LD High	(Note 6)	•	50	5		ns
t <sub>7</sub>	CS/LD Low to SCK High	(Note 6)	•	100	27		ns
t <sub>8</sub>	D <sub>OUT</sub> Propagation Delay	$C_{LOAD} = 15pF$ (Note 6)	•	5	47	150	ns
t <sub>9</sub>	SCK Low to CS/LD Low	(Note 6)	•	30	0		ns
t <sub>10</sub>	CLR Pulse Width	(Note 6)	•	120	41		ns
t <sub>11</sub>	CS/LD High to SCK Positive Edge	(Note 6)	•	30	0		ns
	SCK Frequency	Continuous Square Wave (Note 6) Continuous 28% Duty Cycle Pulse Gated Square Wave	•			3.85 5.55 10	MHz MHz MHz

**Note 1:** Absolute maximum ratings are those values beyond which the life of a device may be impaired.

Note 2: Nonlinearity and monotonicity are defined from code 20 to code

1023. See Applications Information.

Note 3: Digital inputs at OV or  $V_{CC}$ .

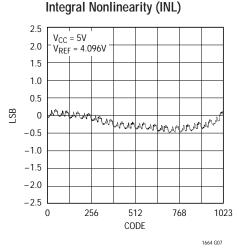
**Note 4:** Load is  $10k\Omega$  in parallel with 100pF.

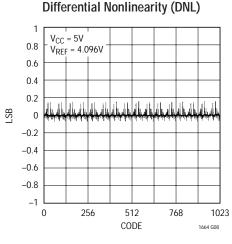
Note 5:  $V_{CC} = V_{REF} = 5V$ . DAC switched between  $0.1V_{FS}$  and  $0.9V_{FS}$ , i.e., codes 102 and 922.

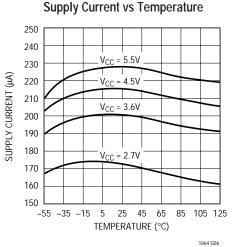
Note 6: Guaranteed by design and not subject to test.

Note 7: Measured at code 20.

## TYPICAL PERFORMANCE CHARACTERISTICS





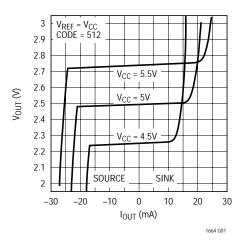


1664 G0

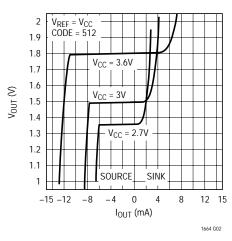


### TYPICAL PERFORMANCE CHARACTERISTICS

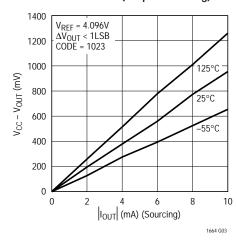
## Midscale Output Voltage vs Load Current



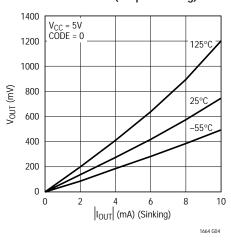
## Midscale Output Voltage vs Load Current



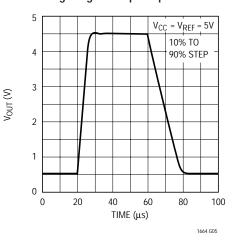
#### Minimum Supply Headroom vs Load Current (Output Sourcing)



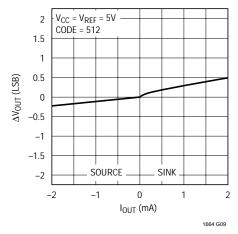
#### Minimum V<sub>OUT</sub> vs Load Current (Output Sinking)



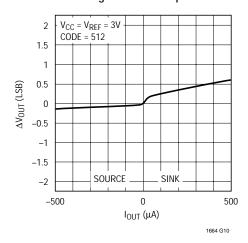
#### Large-Signal Step Response



#### **Load Regulation vs Output Current**



#### **Load Regulation vs Output Current**





### PIN FUNCTIONS

GND (Pin 1): System Ground.

 $V_{OUT\,A}$  to  $V_{OUT\,D}$  (Pins 2–5): DAC Analog Voltage Outputs. The output range is

0 to 
$$\left(\frac{1023}{1024}\right) V_{REF}$$

**REF (Pin 6):** Reference Voltage Input.  $0V \le V_{REF} \le V_{CC}$ .

CS/LD (Pin 7): Serial Interface Chip Select/Load Input. When  $\overline{\text{CS}}/\text{LD}$  is low, SCK is enabled for shifting data on D $_{\text{IN}}$  into the register. When  $\overline{\text{CS}}/\text{LD}$  is pulled high, SCK is disabled and data is loaded from the shift register into the specified DAC register(s), updating the analog output(s). CMOS and TTL compatible.

**SCK (Pin 8):** Serial Interface Clock Input. CMOS and TTL compatible.

 $D_{IN}$  (Pin 9): Serial Interface Data Input. Data on the  $D_{IN}$  pin is shifted into the 16-bit register on the rising edge of SCK. CMOS and TTL compatible.

 $D_{OUT}$  (Pin 10): Serial Interface Data Output. Data appears on  $D_{OUT}$  16 positive SCK edges after being applied to  $D_{IN}$ . May be tied to  $D_{IN}$  of another serial device for daisy-chain operaton. CMOS and TTL compatible.

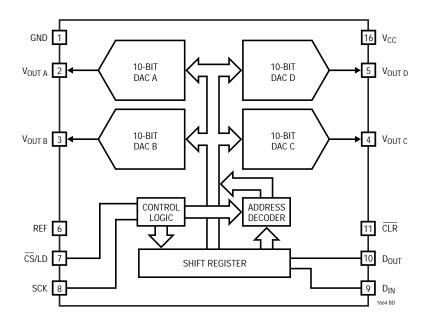
CLR (Pin 11): Asynchronous Clear Input. All internal shift and DAC registers are cleared to zero at the falling edge of the CLR signal, forcing the analog outputs to zero scale. CMOS and TTL compatible.

**NC (Pins 12–15):** Make no electrical connection to these pins.

 $V_{CC}$  (Pin 16): Supply Voltage Input. 2.7V  $\leq$   $V_{CC} \leq$  5.5V.



## **BLOCK DIAGRAM**



## **TIMING DIAGRAM**

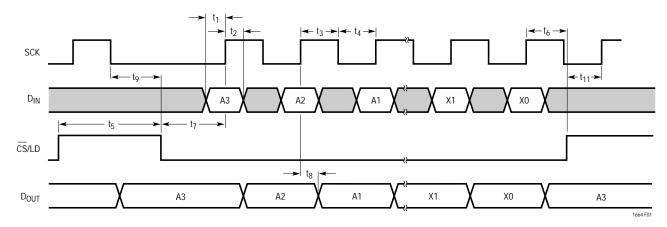


Figure 1



#### Transfer Function

The transfer function is

$$V_{OUT(IDEAL)} = \left(\frac{k}{1024}\right) V_{REF}$$

where k is the decimal equivalent of the binary DAC input code and V<sub>REF</sub> is the voltage at REF (Pin 6).

#### Power-On Reset

The LTC1664 clears the outputs to zero scale when power is first applied, making system initialization consistent and repeatable.

#### **Power Supply Sequencing**

The voltage at REF (Pin 6) should be kept within the range  $-0.2V \le V_{REF} \le V_{CC} + 0.2V$  (see Absolute Maximum Ratings). Particular care should be taken to observe these limits during power supply turn-on and turn-off sequences, when the voltage at  $V_{CC}$  (Pin 16) is in transition.

#### Serial Interface

Referring to Figure 2: With CS/LD held low, data on the  $D_{IN}$  input is shifted into the 16-bit shift register on the positive edge of SCK. The 4-bit DAC address, A3-A0, is loaded first (see Table 2), then the 10-bit input code, D9-D0, ordered MSB-to-LSB in each case. Two don't-care bits, X1-X0, are loaded last. When the full 16-bit input word has been shifted in,  $\overline{CS}$ /LD is pulled high, loading the DAC register with the word and causing the addressed DAC output(s) to update. The clock is disabled internally when  $\overline{CS}$ /LD is high. Note: SCK must be low before  $\overline{CS}$ /LD is pulled low.

The buffered serial output of the shift register is available on the  $D_{OUT}$  pin, which swings from GND to  $V_{CC}$ . Data appears on  $D_{OUT}$  16 positive SCK edges after being applied to  $D_{IN}$ .

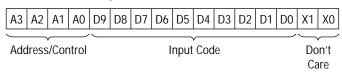
Multiple LTC1664's can be controlled from a single 3-wire serial port (i.e., SCK,  $D_{IN}$  and  $\overline{CS}/LD$ ) by using the included "daisy-chain" facility. A series of m chips is configured by connecting each  $D_{OUT}$  (except the last) to  $D_{IN}$  of the next chip, forming a single 16m-bit shift register. The SCK and  $\overline{CS}/LD$  signals are common to all chips in the chain. In use,  $\overline{CS}/LD$  is held low while m 16-bit words are clocked to  $D_{IN}$  of the first chip;  $\overline{CS}/LD$  is then pulled high, updating all of them simultaneously.

#### Sleep Mode

DAC address  $1110_b$  is reserved for the special Sleep instruction (see Table 2). In this mode, the digital interface stays active while the analog circuits are disabled; static power consumption is thus virtually eliminated. The reference input and analog outputs are set in a high impedance state and all DAC settings are retained in memory so that when Sleep mode is exited, the outputs of DACs not updated by the Wake command are restored to their last active state.

Sleep mode is initiated by performing a load sequence to address  $1110_b$  (the DAC input word D9-D0 is ignored). Once in Sleep mode, a load sequence to any other address (including "No Change" addresses  $0000_b$  and  $1001-1101_b$ ) causes the LTC1664 to Wake. It is possible to keep one or more chips of a daisy chain in continuous Sleep mode by giving the Sleep instruction to these chips each time the active chips in the chain are updated.

Table 1. LTC1664 Input Word





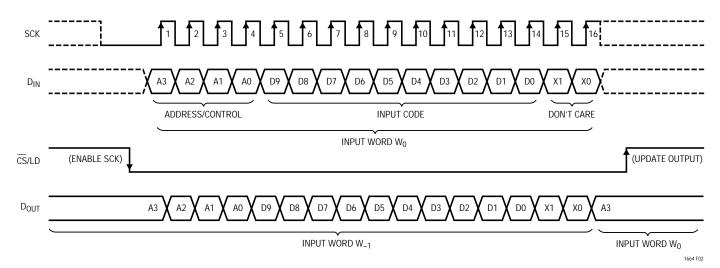


Figure 2. LTC1664 Register Loading Sequence

Table 2. DAC Address/Control Functions

ADDRESS/CONTROL			DL				
А3	A2	<b>A</b> 1	A0	DAC STATUS	SLEEP STATUS		
0	0	0	0	No Change	Wake		
0	0	0	1	Load DAC A	Wake		
0	0	1	0	Load DAC B	Wake		
0	0	1	1	Load DAC C	Wake		
0	1	0	0	Load DAC D	Wake		
0	1	0	1	Reserved			
0	1	1	0	Reserved			
0	1	1	1	Reserved			
1	0	0	0	Reserved			
1	0	0	1	Reserved			
1	0	1	0	Reserved			
1	0	1	1	Reserved			
1	1	0	0	Reserved			
1	1	0	1	Reserved			
1	1	1	0	No Change	Sleep		
1	1	1	1	Load <b>ALL</b> DACs with Same 10-Bit Code	Wake		



#### **Voltage Outputs**

Each of the four rail-to-rail output amplifiers contained in these parts can source or sink up to 5mA. The outputs swing to within a few millivolts of either supply rail when unloaded and have an equivalent output resistance of  $85\Omega$  when driving a load to the rails. The output amplifiers are stable driving capacitive loads up to 1000pF.

A small resistor placed in series with the output can be used to achieve stability for any load capacitance. A 1 $\mu$ F load can be successfully driven by inserting a 20 $\Omega$  resistor; a 2.2 $\mu$ F load needs only a 10 $\Omega$  resistor. In either case, larger values of resistance, capacitance or both may be safely substituted for the values given.

#### Rail-to-Rail Output Considerations

In any rail-to-rail voltage output DAC, the output is limited to voltages within the supply range.

If the DAC offset is negative, the output for the lowest codes limits at 0V as shown in Figure 3b.

Similarly, limiting can occur near full scale when the REF pin is tied to  $V_{CC}$ . If  $V_{REF} = V_{CC}$  and the DAC full-scale error (FSE) is positive, the output for the highest codes limits at  $V_{CC}$  as shown in Figure 3c. No full-scale limiting can occur if  $V_{REF}$  is less than  $V_{CC}$  – FSE.

Offset and linearity are defined and tested over the region of the DAC transfer function where no output limiting can occur.



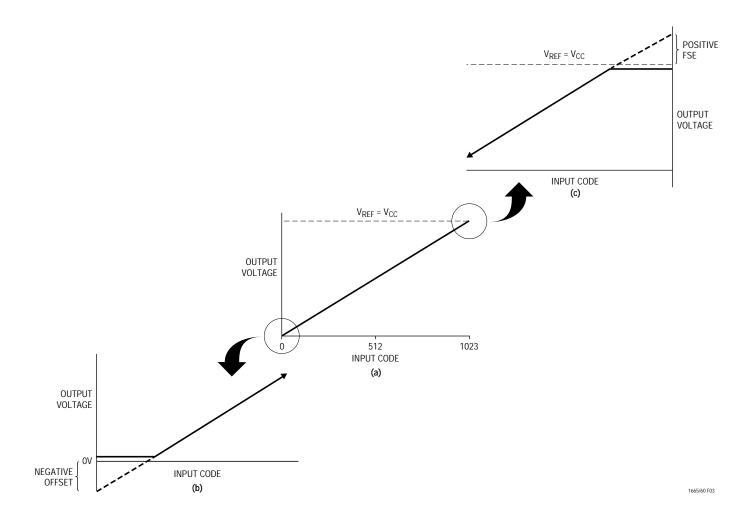
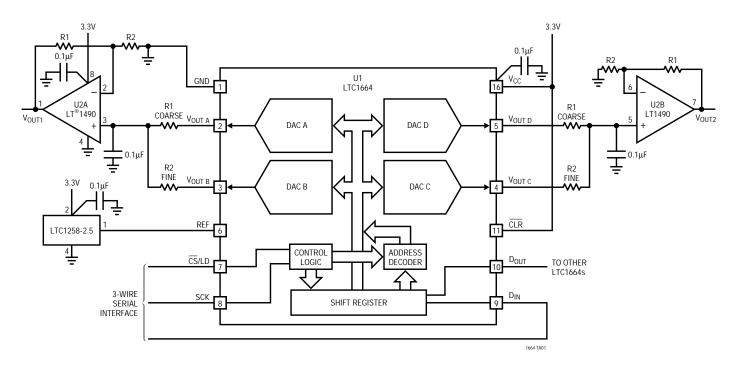


Figure 3. Effects of Rail-to-Rail Operation On a DAC Transfer Curve. (a) Overall Transfer Function (b) Effect of Negative Offset for Codes Near Zero Scale (c) Effect of Positive Full-Scale Error for Input Codes Near Full Scale When  $V_{REF} = V_{CC}$ 



## TYPICAL APPLICATIONS

A Low Power Dual Trim Circuit with Coarse/Fine Adjustment



$$R2 >> R1$$

$$V_{OUT 1} = V_{OUT A} + \left(\frac{R1}{R2}\right) V_{OUT B}$$

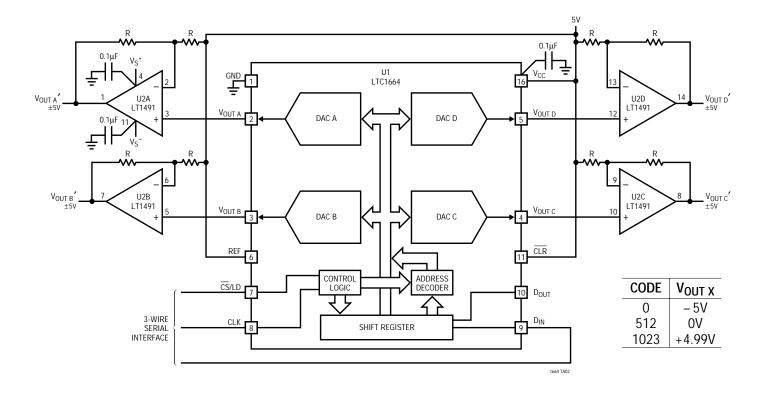
Similarly V<sub>OUT 2</sub>

Example: For R1 = 110  $\!\Omega$  and R2 = 11k,

 $V_{OUT 1} = V_{OUT A} + 0.01 V_{OUT B}$ 

## **TYPICAL APPLICATIONS**

#### A 4-Channel Bipolar Output Voltage Circuit Configuration



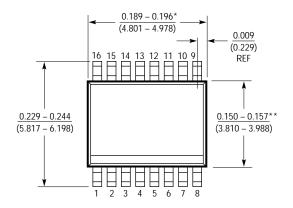


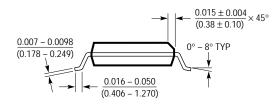
## PACKAGE DESCRIPTION

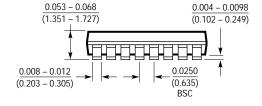
Dimensions in inches (millimeters) unless otherwise noted.

#### GN Package 16-Lead Plastic SSOP (Narrow 0.150)

(LTC DWG # 05-08-1641)







- \* DIMENSION DOES NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.006" (0.152mm) PER SIDE
- \*\* DIMENSION DOES NOT INCLUDE INTERLEAD FLASH. INTERLEAD FLASH SHALL NOT EXCEED 0.010" (0.254mm) PER SIDE

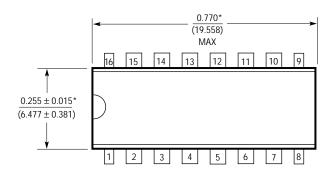
GN16 (SSOP) 1098

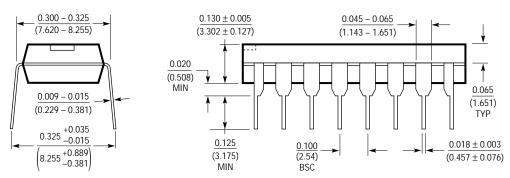


## PACKAGE DESCRIPTION

 $\label{lem:decomposition} \mbox{Dimensions in inches (millimeters) unless otherwise noted.}$ 

#### N Package 16-Lead PDIP (Narrow 0.300) (LTC DWG # 05-08-1510)





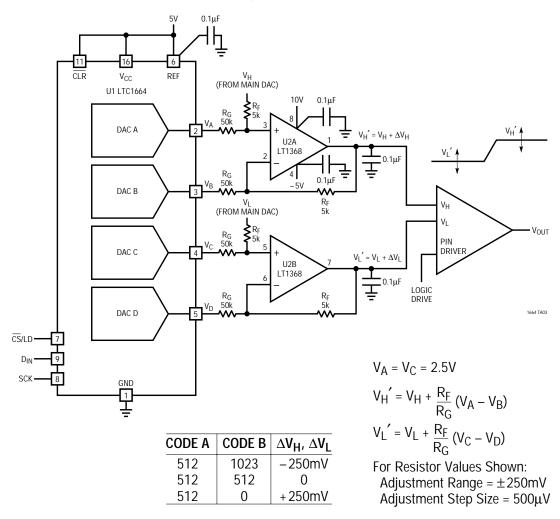
\*THESE DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.010 INCH (0.254mm)

N16 1098



### TYPICAL APPLICATION





### **RELATED PARTS**

PART NUMBER	DESCRIPTION	COMMENTS
LTC1665/LTC1660	Octal 8/10-Bit V <sub>OUT</sub> DAC in 16-Pin Narrow SSOP	V <sub>CC</sub> = 2.7V to 5.5V, Micropower, Rail-to-Rail Output
LTC1661	Dual 10-Bit V <sub>OUT</sub> DAC in 8-Lead MSOP Package	V <sub>CC</sub> = 2.7V to 5.5V Micropower, Rail-to-Rail Output
LTC1663	Single 10-Bit V <sub>OUT</sub> DAC with 2-Wire Interface in SOT-23 Package	V <sub>CC</sub> = 2.7V to 5.5V, Internal Reference, 60μA
LTC1446/LTC1446L	Dual 12-Bit V <sub>OUT</sub> DACs in SO-8 Package with Internal Reference	LTC1446: V <sub>CC</sub> = 4.5V to 5.5V, V <sub>OUT</sub> = 0V to 4.095V LTC1446L: V <sub>CC</sub> = 2.7V to 5.5V, V <sub>OUT</sub> = 0V to 2.5V
LTC1448	Dual 12-Bit V <sub>OUT</sub> DAC in SO-8 Package	$V_{CC}$ = 2.7V to 5.5V, External Reference Can Be Tied to $V_{CC}$
LTC1454/LTC1454L	Dual 12-Bit V <sub>OUT</sub> DACs in SO-16 Package with Added Functionality	LTC1454: V <sub>CC</sub> = 4.5V to 5.5V, V <sub>OUT</sub> = 0V to 4.095V LTC1454L: V <sub>CC</sub> = 2.7V to 5.5V, V <sub>OUT</sub> = 0V to 2.5V
LTC1458/LTC1458L	Quad 12-Bit Rail-to-Rail Output DACs with Added Functionality	LTC1458: V <sub>CC</sub> = 4.5V to 5.5V, V <sub>OUT</sub> = 0V to 4.095V LTC1458L: V <sub>CC</sub> = 2.7V to 5.5V, V <sub>OUT</sub> = 0V to 2.5V
LTC1590	Dual 12-Bit I <sub>OUT</sub> DAC in SO-16 Package	V <sub>CC</sub> = 4.5V to 5.5V, 4-Quadrant Multiplication
LTC1659	Single Rail-to-Rail 12-Bit V <sub>OUT</sub> DAC in 8-Lead MSOP Package V <sub>CC</sub> : 2.7V to 5.5V	Low Power Multiplying $V_{OUT}$ DAC. Output Swings from GND to REF. REF Input Can Be Tied to $V_{CC}$
LT1460	Micropower Precision Series Reference, 2.5V, 5V, 10V Versions	0.075% Max, 10ppm/°C Max, Only 130μA Supply Current